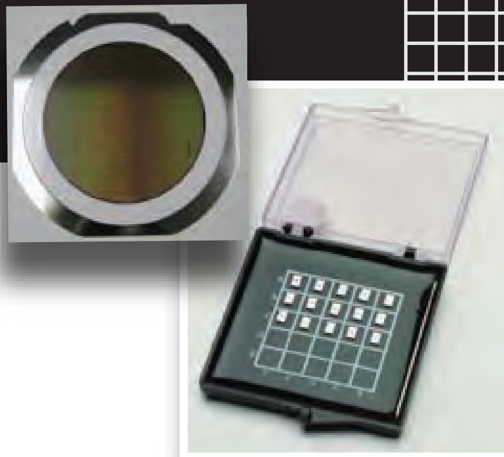
Quik Pak™

Microelectronic Packaging & Assembly Solutions

WAFER PREPARATION & DIE SORT



Capabilities:

- Wafer Dicing up to 300mm
- Backgrinding
- Sillicon, Quartz, Glass, Ceramic, Laminates, etc.
- Multi-Project Wafers (MPW)
- Die Sort into Various Media (Gel-Pak, Waffle Pack)
- Same-Day Service Available
- Prototype to Medium Volume
- Cleanroom Environment
- Outstanding Quality and Customer Service

Whether you are a fabless Semiconductor company needing a complete turn-key packaging and assembly solution for your new designs or an Integrated Device Manufacturer (IDM) with internal prototype assembly capability, Quik-Pak can provide wafer and die preparation services to meet your requirements.

Wafer Dicing
Disco automatic equipment will precisely dice your wafers or substrates including multi-project or "pizza" wafers. Kef widths as narrow as 15µm. Automatic kerf width/chip-out monitoring.

Silicon Wafer Coring
Silicon wafer coring from wafers as large as 12" (305mm) for custom extraction of smaller development wafers.

Backgrinding
Wafers can be thinned down to 52µm to accommodate the latest package technology and stacked die applications.

Pick & Place
Have your die sorted into Gel-Pak's® or waffle packs.

Quick-Turn Service
When you need to meet a project or customer deadline, you can count on Quik-Pak's reliable on-time delivery options including same-day expedited service. In fact, we can receive a wafer in the morning and ship completely assembled devices by the end of the day.

When you require a full turnkey provider of production-quality prototype parts for internal testing or customer samples, Quik-Pak is the answer. Services include Wafer Backgrinding &Dicing, Package Procurement & Open Cavity Preparation, Die Attach, Wire boning, Encapsulation, Remolding and Marking.

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